

This listing of the claims will replace all prior versions, and listings, of claims in the present application:

LISTING OF THE CLAIMS:

1-15. (Cancelled).

16. (Currently Amended) A MOSFET device comprising a silicon substrate having shallow trench isolation STI and source and drain regions located therein, a gate dielectric and a gate stack located on said silicon substrate between the source and drain regions, and a fluorine doped low K dielectric oxide gate spacers located on sidewalls of said gate stack, said fluorine doped low K dielectric oxide gate spacer having a fluorine content of about $1\text{E}14$ to $2\text{E}16\text{ cm}^{-2}$, wherein the said fluorine doped low K dielectric oxide gate spacer is in direct contact with an overlying silicon nitride oxide layer and at least a portion of said source and drain regions are essentially free of fluorine directly contacts said silicon nitride oxide layer.

17. (Previously Presented) The MOSFET device of Claim 16 wherein said fluorine doped low K dielectric oxide gate spacer has a dielectric constant value in a range of 3.3 to 4.0.

18. (Previously Presented) The MOSFET device of Claim 16 wherein said fluorine doped low K dielectric oxide gate spacer has a dielectric constant value of substantially 3.3.

19. (Cancelled).

20. (Currently Amended) The MOSFET device of Claim 16 ~~further comprising a~~ wherein
said silicon nitride oxide layer located on at least overlays said gate stack.

21. (Currently Amended) A MOSFET device comprising a silicon substrate having shallow trench isolation (STI) located therein, a gate dielectric and a gate stack located on said silicon substrate, a fluorine doped low K dielectric oxide gate spacer located on sidewalls of said gate stack, and a silicon nitride oxide layer overlaying and contacting said gate stack, said fluorine doped low K dielectric oxide gate spacer, and remaining surfaces of the silicon substrate, wherein no material with a dielectric constant greater than 4.0 is present between said fluorine doped low K dielectric oxide gate spacer and said silicon nitride oxide layer.